

Molded Interconnect Device (MID) Market by Product Type (Antennae & Connectivity, Sensor),by Process (Laser Direct Structuring, Two-shot Molding), by Industry (Consumer Electronics, Telecommunication, Medical) and Geography - Global Forecast to 2027

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Abstracts

The molded interconnect device (MID) market is expected to grow from USD1.4 billion in 2022 to USD 2.7billion by 2027; it is expected to grow at a CAGR of 13.6% during the forecast period. The major driving factors for the growth of the molded interconnect device (MID)market include the growing advancement in automotive vertical.

Connectors and switches to have significant market size of molded interconnect device (MID)market during the forecast period

Connectors and switches are mainly used in automotive and medical industries. In the automotive Vertical, connectors find application in navigation devices, infotainment systems, cameras, and so on. MID technology is used in connectors to improve assembly operability, provide electrical and mechanical reliability, and offer compactness. Limited space issue in switchescan be solved using MID technology

Telecommunication to have second highestCAGR during the forecast period.

In the telecommunications sector, MIDs are used in mobile phones and landline phones, remote controls, and the global telecommunications infrastructure such as satellites, base equipment, and network equipment. Generally, telecommunications based on the network are used in three different broad business areas, namely, central office, outside plants, and mobility. Central office refers to large facilities where very high-volume communications are switched and processed; outside plants refer to

switching stations where distributive switching occurs for commercial and home landlines; and the third area is mobility, where tower-based power and grounding supports mobile communication transmission.

US to grow with highest CAGR in North America during the forecast period.

The US is the major revenue generator for players dealing in MIDs in North America. In 2021, the US accounted for highest CAGR of the MID market in North America, owing to the presence of leading manufacturers such as Molex, Arlington Plating Company, Amphenol Corporation, and Kyocera AVX Corporation. These manufacturers provide a comprehensive range of MID products to enhance the electrical connectivity and performance of the equipment or devices across various applications. Consumer electronics, medical, telecommunication, and industrial applications are driving the demand for MIDs in the US. The consumer electronics market in the US has been continuously growing. Moreover, it has been observed that the demand for miniaturized packages has started gaining momentum in consumer electronics, automotive components, medical equipment, and other devices.

In the process of determining and verifying the market size for several segments and subsegments gathered through secondary research, extensive primary interviews have been conducted with key officials in the molded interconnect device (MID) market. Following is the breakup of the profiles of primary participants for the report.

By Company Type: Tier 1 – 35 %, Tier 2 – 45%, and Tier 3 – 20%

By Designation: C-Level Executives – 35%, Directors- 25%, and Others – 40%

By Region: North America – 45%, Asia Pacific – 30%, Europe- 20% and RoW – 5%

The molded interconnect device (MID) market comprises major players are Molex (US), TE Connectivity (Switzerland), Amphenol Corporation (US), LDK Laser & Electronics (Germany), and Taoglas (Dublin), Harting (Germany), Arlington Plating Company (US), MID Solutions (Germany), 2E Mechatronic (Germany), KYOCERA AVX (US) and Johnan (Japan), Teprosa (Germany), Sunway Communication (China), Axon Cable (France), S2P (France), Suzhou Cicor Technology (China), TactoTek (Finland), DuraTech (US), Tekra (US), Yomura Technologies (Taiwan), MacDermid Alpha Electronics (US), Galtronics (US), Yazaki Corporation (Japan), Chogori Technology

(Japan), Suzhou Zeeteq Electronics (Japan), Toyo Connectors (Japan) and SINOPLAST (China).

Research Coverage

The report defines, describes, and forecasts the molded interconnect device (MID) market based on product type, process, vertical and geography. It provides detailed information regarding factors such as drivers, restraints, opportunities, and challenges influencing the growth of the molded interconnect device (MID) market. It also analyzes competitive developments such as product launches, acquisitions, expansions, contracts, partnerships, and developments carried out by the key players to grow in the market.

Reasons to Buy This Report

The report will help leaders/new entrants in the molded interconnect device (MID) market in the following ways:

1. The report segments the molded interconnect device (MID) market comprehensively and provides the closest market size estimation for all subsegments across regions.
2. The report will help stakeholders understand the pulse of the market and provide them with information on key drivers, restraints, challenges, and opportunities about molded interconnect device (MID) market.
3. The report will help stakeholders understand their competitors better and gain insights to improve their position in the molded interconnect device (MID) market. The competitive landscape section describes the competitor ecosystem.

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*Details on Business overview, Products offered, Recent Developments, MNM view might not be captured in case of unlisted companies.

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